Plasma Etch Tech 2008

Presented by
The Kavli Nanoscience Institute
California Institute of Technology and
Oxford Instruments

July 17 – 18, 2008
Caltech Campus - Winnett Lounge
Pasadena, California

Thursday, July 17th
Presentations, Panel Discussions and a Networking Lunch

Dr. Ivo Rangelow, Technical University Ilmenau, Plasma Simulation Program
Dr. Axel Scherer, Nечes Professor of Electrical Engineering, Applied Physics
and Physics; Co-Director, Kavli Nanoscience Institute, Caltech
Dr. Oskar Painter, Assistant Professor of Applied Physics, Caltech
Dr. Deirdre Olynick, Staff Scientist, Nanofabrication Facility, Lawrence Berkeley National Lab
Robert Gunn, Application Team Leader, Oxford Instruments Plasma Technology
Scott Sitzman, Application Scientist, Oxford Instruments NanoAnalysis
Dr. Michael Roukes, Professor of Physics, Applied Physics, and Bioengineering; Co-Director, Kavli
Nanoscience Institute, Caltech
Dr. Alex Buxbaum, Staff Applications Engineer, FEI

Friday, July 18th
Workshops

1. DRIE etching of silicon microstructures for MEMS applications - PLASMALAB 100 ICP 380 for
MEMS

2. Cryo-etch of silicon for optical waveguides and mirrors - PLASMALAB 100 ICP 380 - with wide range
temp electrode (-150C to 450C)

3. Low-T CVD nitride and oxide growth - PLASMALAB 100 PECVD

4. Anisotropic GaAs etching with halogen (Chlorine) gas chemistries - PLASMALAB 100 ICP380

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